

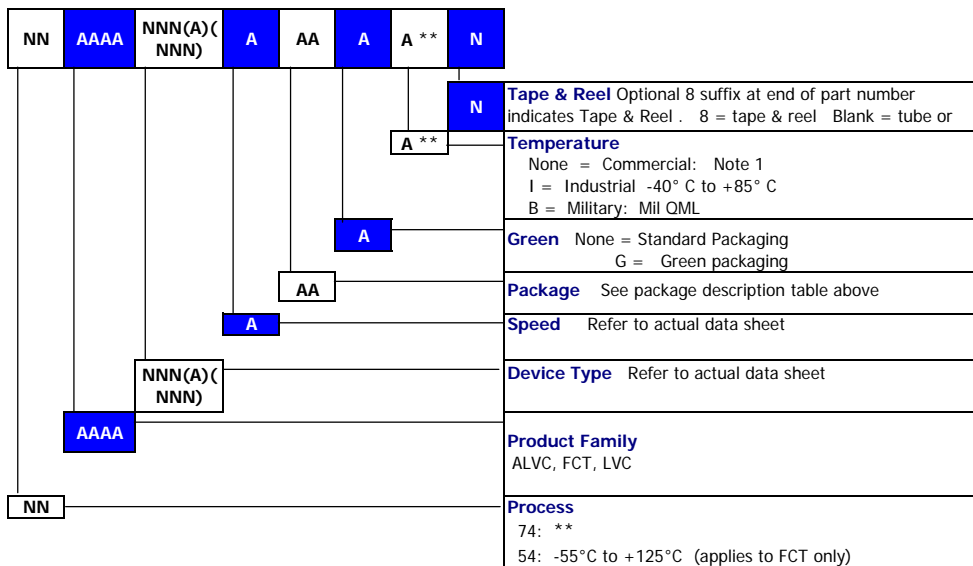


**DIGITAL LOGIC PRODUCTS**  
**Ordering Information**  
**Package Description Table**

IDT ID	Abbr	Description	IDT ID	Abbr	Description
D	CDIP	Ceramic Dual In-Line Package - mil only	DC	SOIC	Small Outline Integrated Circuit
E	CPACK	Ceramic Package	SO	SOIC	Small Outline Integrated Circuit
BF	CABGA	Fine Pitch Ball Grid Array	S1	SOIC	Small Outline Integrated Circuit
L	LCC	Ceramic Leadless Chip Carrier - mil only	PV	SSOP	Shrink Small Outline Package
Q	QSOP	Quarter Size Small Outline Package	PY	SSOP	Shrink Small Outline Package
Q1	QVSOP	Quarter Size Very Small Outline Package	PA	TSSOP	Thin Shrink Small Outline Package
Q2	QVSOP	Quarter Size Very Small Outline Package	PG	TSSOP	Thin Shrink Small Outline Package
Q3	QVSOP	Quarter Size Very Small Outline Package	PF	TVSOP	Thin Very Small Outline Package

**STANDARD LOGIC PRODUCTS**  
**Part Number Description**

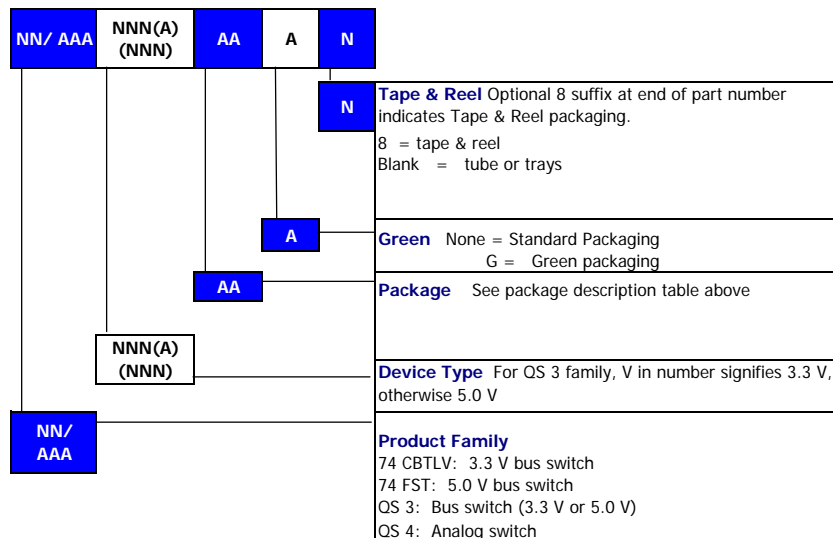
A = Alpha character N = Numeric character



\*\* Check data sheet for temp range (most FCT and all ALVC, LVC are -40° C to +85° C

**BUS SWITCH**  
**Part Number Description**

A = Alpha character N = Numeric character



\*\* All Bus Switches are "I" temperature -40° C to +85° C